

# 4V Drive Pch + Pch MOSFET

# QS8J4

#### Structure

Silicon P-channel MOSFET

#### ● Features

- 1) Low on-resistance.
- 2) High power package(TSMT8).
- 3) Low voltage drive(4V drive).

# Application

Switching

#### Packaging specifications

	<u> </u>	
Type	Package	Taping
	Code	TR
	Basic ordering unit (pieces)	3000
QS8J4		0

# ● Absolute maximum ratings (Ta = 25°C)

Parameter		Symbol	Limits	Unit	
Drain-source voltage		$V_{DSS}$	-30	V	
Gate-source voltage		$V_{GSS}$	±20	V	
Drain current	Continuous	$I_D$	±4	Α	
	Pulsed	I <sub>DP</sub> *1	±16	Α	
Source current (Body Diode)	Continuous	l <sub>s</sub>	-1	Α	
	Pulsed	I <sub>sp</sub> *1	-16	Α	
Power dissipation		P <sub>D</sub> *2	1.5	W / TOTAL	
		' Б -	1.25	W / ELEMENT	
Channel temperature		Tch	150	°C	
Range of storage temperature		Tstg	-55 to +150	°C	

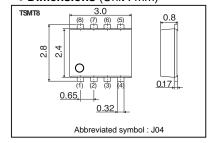
<sup>\*1</sup> Pw≤10µs, Duty cycle≤1%

#### • Thermal resistance

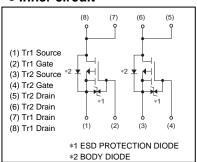
Parameter	Symbol	Limits	Unit
Channel to Ambient	Rth (ch-a)*	83.3	°C / W /TOTAL
Chambe to Ambient	Kill (Cli-a)	100	°C/W/ELEMENT

<sup>\*</sup> Each terminal mounted on a ceramic board.

# Dimensions (Unit : mm)



#### • Inner circuit



1/5

<sup>\*2</sup> Each terminal mounted on a ceramic board.

# ● Electrical characteristics (Ta = 25°C)

<It is the same ratings for Tr1 and Tr2.>

Parameter	Symbol	Min.	Тур.	Max.	Unit	Conditions
Gate-source leakage	$I_{GSS}$	-	-	±10	μA	$V_{GS}=\pm20V, V_{DS}=0V$
Drain-source breakdown voltage	V <sub>(BR)DSS</sub>	-30	-	-	V	I <sub>D</sub> =-1mA, V <sub>GS</sub> =0V
Zero gate voltage drain current	I <sub>DSS</sub>	1	-	-1	μA	$V_{DS}$ =-30V, $V_{GS}$ =0V
Gate threshold voltage	V <sub>GS (th)</sub>	-1.0	1	-2.5	>	$V_{DS}=-10V$ , $I_{D}=-1mA$
Otatia duain assuma an atata	*		40	56		I <sub>D</sub> =-4A, V <sub>GS</sub> =-10V
Static drain-source on-state resistance	R <sub>DS (on)</sub>	1	55	77	mΩ	I <sub>D</sub> =-2A, V <sub>GS</sub> =-4.5V
		1	60	84		$I_D=-2A$ , $V_{GS}=-4V$
Forward transfer admittance	I Y <sub>fs</sub> ľ*	3	-	-	S	I <sub>D</sub> =-4A, V <sub>DS</sub> =-10V
Input capacitance	C <sub>iss</sub>	-	800	-	pF	V <sub>DS</sub> =-10V
Output capacitance	C <sub>oss</sub>	-	120	-	pF	V <sub>GS</sub> =0V
Reverse transfer capacitance	C <sub>rss</sub>	1	110	-	pF	f=1MHz
Turn-on delay time	t <sub>d(on)</sub> *		8	-	ns	I <sub>D</sub> =-2A, V <sub>D</sub> ≒-15V
Rise time	t <sub>r</sub> *	1	20	-	ns	V <sub>GS</sub> =-10V
Turn-off delay time	t <sub>d(off)</sub> *	-	80	-	ns	$R_L=7.5\Omega$
Fall time	t <sub>f</sub> *	-	50	-	ns	$R_G=10\Omega$
Total gate charge	Q <sub>g</sub> *	-	8.4	-	nC	I <sub>D</sub> =-4A, V <sub>D</sub> ; -15V
Gate-source charge	Q <sub>gs</sub> *	-	3.0	-	nC	V <sub>GS</sub> =-5V
Gate-drain charge	Q <sub>gd</sub> *	-	3.5	-	nC	$R_L=3.8\Omega$ , $R_G=10\Omega$

<sup>\*</sup>Pulsed

# ●Body diode characteristics (Source-Drain) (Ta = 25°C)

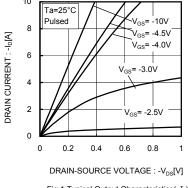
<It is the same ratings for Tr1 and Tr2.>

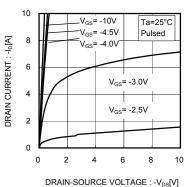
Parameter	Symbol	Min.	Тур.	Max.	Unit	Conditions
Forward Voltage	V <sub>SD</sub> *	-	-	-1.2	V	I <sub>s</sub> =-4A, V <sub>GS</sub> =0V

<sup>\*</sup>Pulsed

2/5

#### Electrical characteristic curves





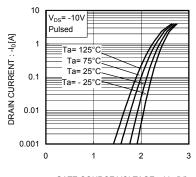
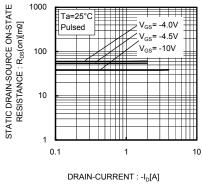
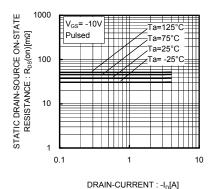


Fig.1 Typical Output Characteristics( I)

Fig.2 Typical Output Characteristics( II)

GATE-SOURCE VOLTAGE: -V<sub>GS</sub>[V] Fig.3 Typical Transfer Characteristics





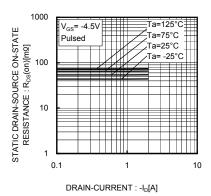
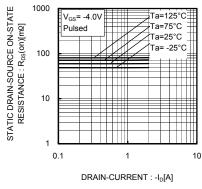
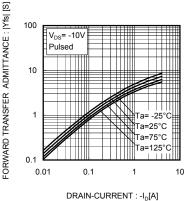


Fig.4 Static Drain-Source On-State Resistance vs. Drain Current( I )

Fig.5 Static Drain-Source On-State Resistance vs. Drain Current(  ${\rm I\hspace{-.1em}I}$  )

Fig.6 Static Drain-Source On-State Resistance vs. Drain Current( III )





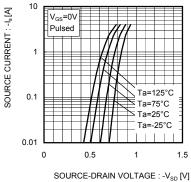


Fig.7 Static Drain-Source On-State Resistance vs. Drain Current( IV)

Fig.8 Forward Transfer Admittance vs. Drain Current

Fig.9 Reverse Drain Current vs. Sourse-Drain Voltage

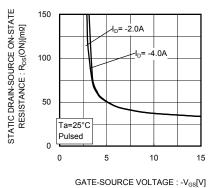


Fig.10 Static Drain-Source On-State
Resistance vs. Gate Source Voltage

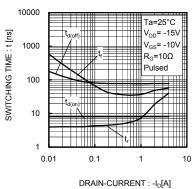
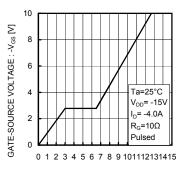
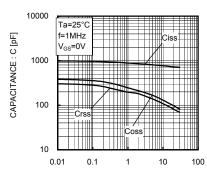


Fig.11 Switching Characteristics



TOTAL GATE CHARGE : Qg [nC] Fig.12 Dynamic Input Characteristics



DRAIN-SOURCE VOLTAGE : -V<sub>DS</sub>[V]
Fig.13 Typical Capacitance
vs. Drain-Source Voltage

# Measurement circuits

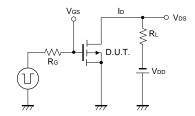


Fig.1-1 Switching Time Measurement Circuit

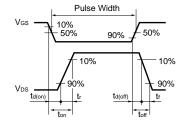


Fig.1-2 Switching Waveforms

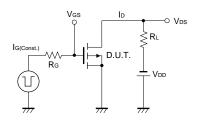


Fig.2-1 Gate Charge Measurement Circuit

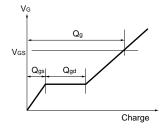


Fig.2-2 Gate Charge Waveform

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